



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application

Inventors: Heung-Kyu KWON et al.

Docket No.: 62230-000002

Application No.: 09/464,322

Group Art Unit: 2815

Filing Date: December 15, 1999

Examiner: Chris C. Chu

Title: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF FABRICATING
THE SAME

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Honorable Commissioner for Patents
Washington, D.C. 20231

Date: February 19, 2003

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